

Customer No.: 31561
Docket No.: 13369-US-PA
Application No.: 10/710,930

In The Specification

Page 1, [0005], please rewrite as follows: "Fig. 1 is a schematic cross-sectional view of a conventional image sensor. As shown in Fig. 1, a conventional image sensor 100 comprises a chip 110, a glass plate 120 and a plastic frame 130. The plastic frame 130 is set up between the chip 110 and the glass plate 120. The chip 110, the glass plate 120 and the plastic frame 130 together constitute a space 100a. The chip 110 is a CMOS image sensor chip, for example, capable of receiving an incident light beam passing through the glass plate 120 and outputting electrical signals. It should be noted that the glass plate 120 and the plastic frame 130 assembly is an effective barrier against the infiltration of dust particles or moisture into the ~~chip-sensor~~ 100 leading to chip 110 failure."

Page 1, [0049], please rewrite as follows: " Hereinafter, an assembling method of the present invention for alignment assembly ~~will~~ will be described by, for example but not limited to, using the assembling device 300 as an exemplary example. First, the assembling device 300 is opened (as shown in Fig. 2A). Next, a first plate 210 and a second plate 220 are placed on the first carrier area 310a of the first carrier plate 310 and the second carrier area 320a of the second carrier plate 320 respectively. Thereafter, a vacuum pump with pipeline (not shown) linking to the first air channel 312 and the second air channel 322 is activated to produce a partial vacuum. Hence, the first plate 210 and the second plate 220 are attached to the first carrier plate 310 and the second carrier plate 320 respectively through suction. The second carrier plate 320 is then flipped over to stack on top of the first carrier 310. Thus, the first carrier plate 310, the

Customer No.: 31561
Docket No.: 13369-US-PA
Application No.: 10/710,930

second carrier plate 320 and the sealing ring 316 together form a sealed chamber. The vacuum pump is also linked to the third air channel 314 through a pipeline. When the air inside the sealed chamber is pumped by the vacuum pump via the third air channel 314, the pressure inside the chamber is pumped to a first pressure below the pressure outside the sealed chamber. In one embodiment of the present invention, the first pressure is lower than the pressure outside the sealed chamber in a range of about 40kPa to about 50kPa."